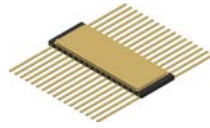


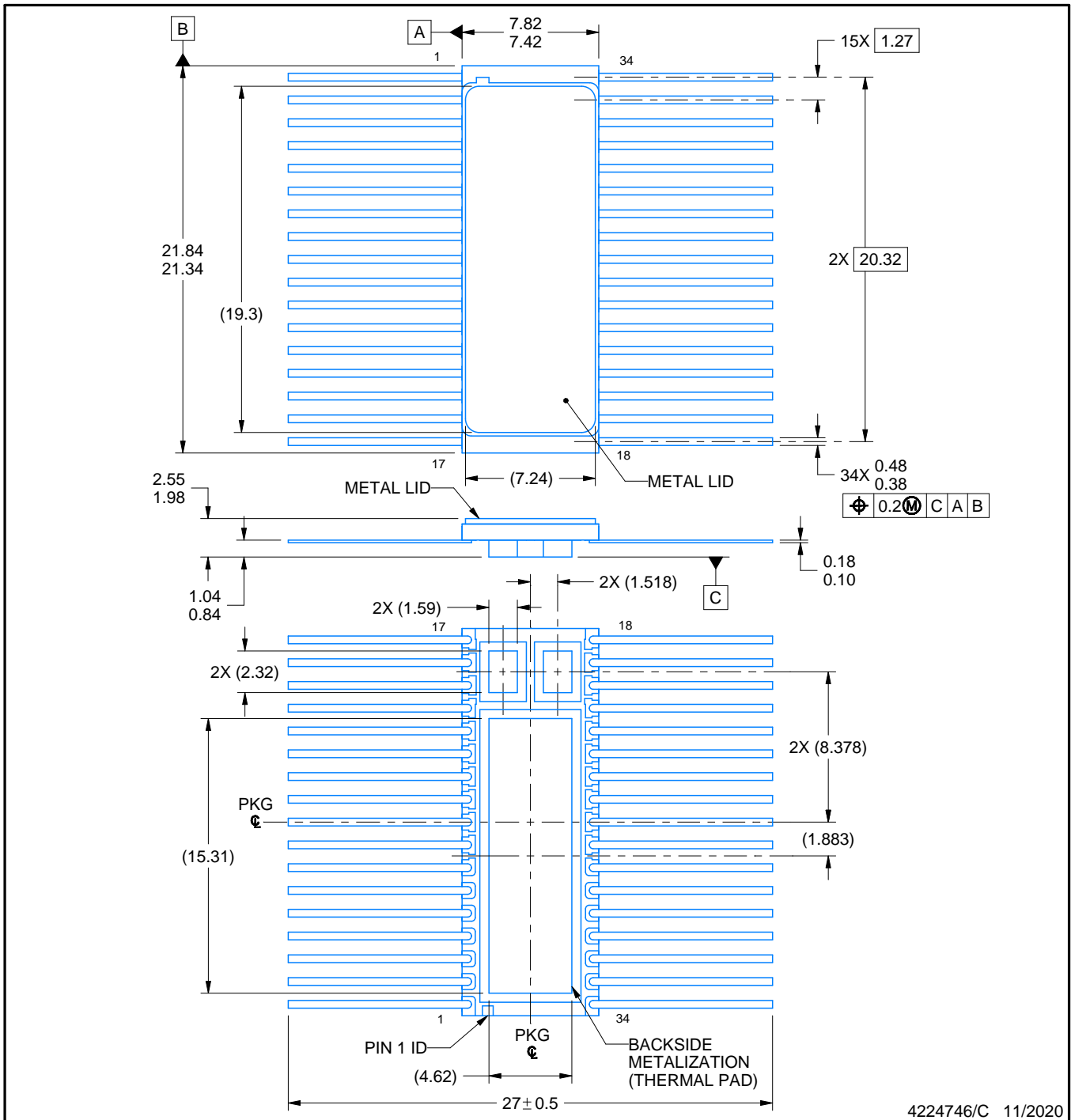
HKY0034A



PACKAGE OUTLINE

CFP - 2.55 mm max height

CERAMIC FLATPACK



4224746/C 11/2020

NOTES:

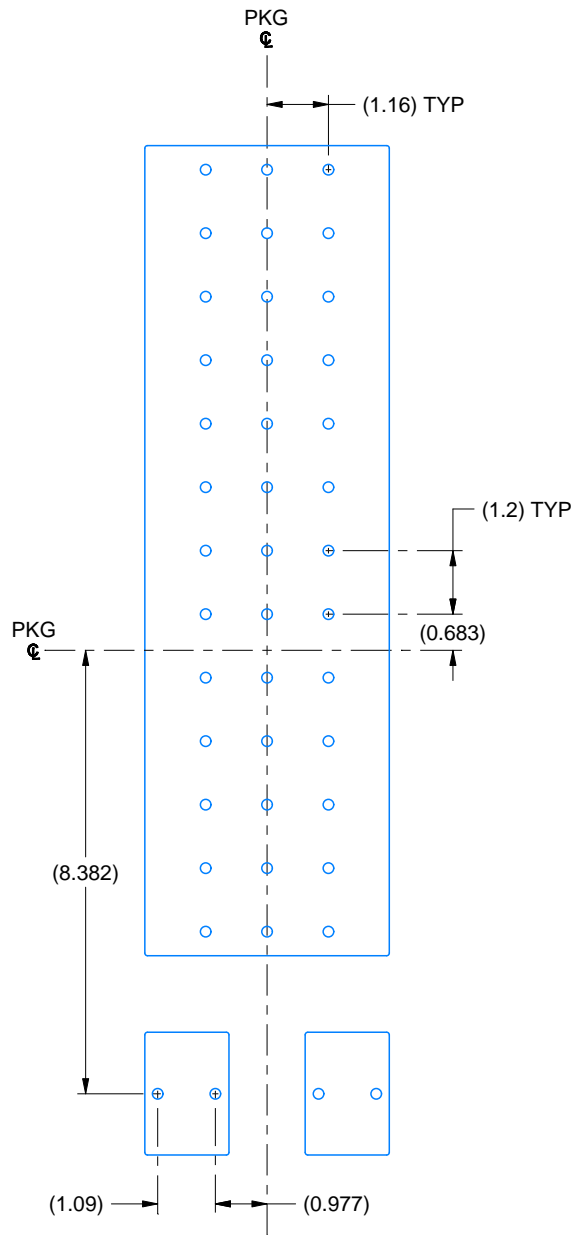
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a metal lid. The lid is connected to Pin 1.
4. The leads are gold plated.
5. Metal lid is connected to backside pad metallization

EXAMPLE BOARD LAYOUT

HKY0034A

CFP - 2.55 mm max height

CERAMIC FLATPACK



HEATSINK LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:7X

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